

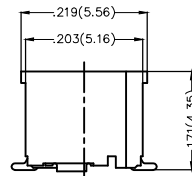
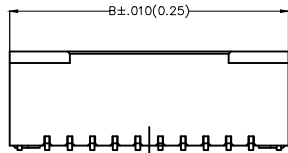
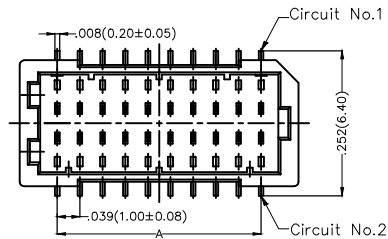
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Electrical

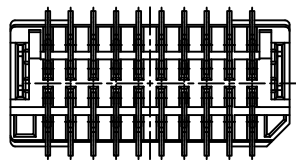
Current Rating: 1A AC(rms)/DC(AWG32)
Voltage Rating: 50V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 100 MΩ MIN
Withstanding Voltage: 500V AC r.m.s
Temperature Range-Operating: -25°C ~ +85°C

Material and Plating

Housing: PA9T(UL 94V-0)
Contact Pin: Brass
Plating: Gold Plated



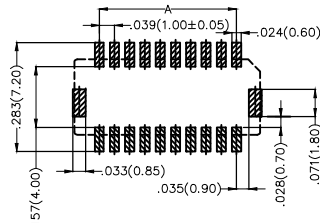
Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
10	FWF10003-D10S14W5M	.157(4.00)	.287(7.30)
12	FWF10003-D12S14W5M	.276(5.00)	.406(8.30)
16	FWF10003-D16S14W5M	.276(7.00)	.406(10.30)
20	FWF10003-D20S14W5M	.354(9.00)	.484(12.30)
30	FWF10003-D30S14W5M	.551(14.00)	.681(17.30)
40	FWF10003-D40S14W5M	.748(19.00)	.878(22.30)
50	FWF10003-D50S14W5M	.945(24.00)	1.075(27.30)




Ordering Information

FWF 100 03 — D XX S 1 4 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF-Wafer	2	Series Number 100-Pitch1.0mm	3	Distinction No. 03	4	Row Option Double Row	5	Circuits XX	6	Entry Angle S-180° Vertical
7	Plating 1-Gold Plated	8	Material-Resin 4-PA9T	9	Color-Resin W5-White	10	Packaging M-Reel				



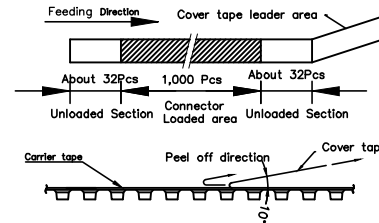
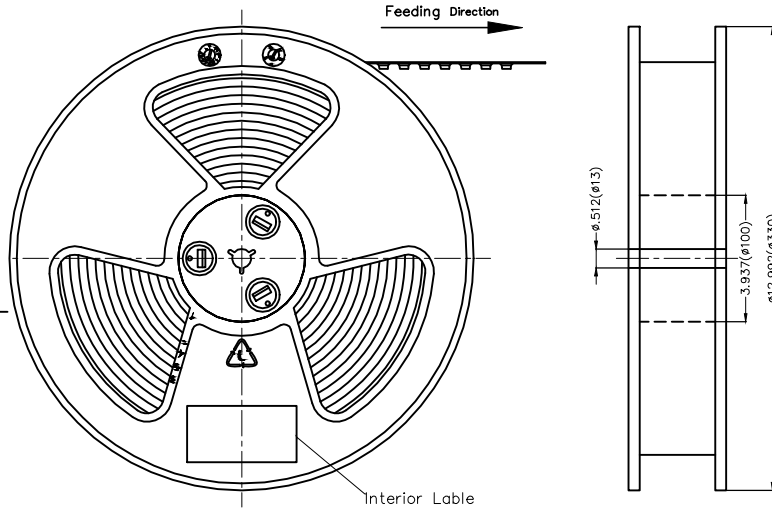
Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF10003-DXXS14W5M		ITEM NO. FWF10003	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X.'±5' X.'±2' X.X'±1' X.XXX'±0.5'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		
SCALE 5:1	SIZE A4	DRAWN BY CHERRY		DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

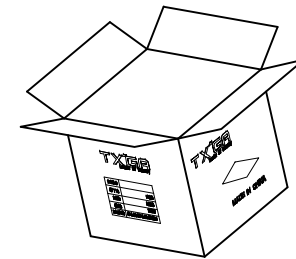
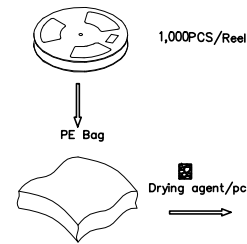
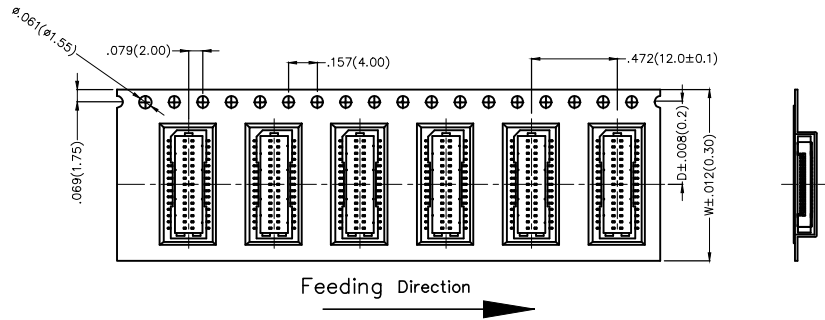
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

- 10 sprocket hole cumulative tolerance ± 0.2
- Carrier camber is within 1.0mm in 250mm
- Material: White Conductive polystyrene Alloy 100% recyclable
- All dimensions meet EIA-481-3 requirements
- Peel off force of cover tape & carrier tape: 20g~130g (0.2N~1.3N)
- Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)	
	D	W
10	.453(11.50)	.945(24.00)
12	.453(11.50)	.945(24.00)
16	.453(11.50)	.945(24.00)
20	.453(11.50)	.945(24.00)
30	.453(11.50)	.945(24.00)
40	.798(20.20)	1.732(44.00)
50	.798(20.20)	1.732(44.00)



 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Leader Of Industry
	X.±.012(0.30)	X.'±5'	FRANK	28/JUN/13	FWF10003-DXXS14W5M	FWF10003	
DESIGN UNITS Inch (metric)	X.XX±.008(0.20)	.X'±2'	CHECKED BY	DATE	TITLE		REV 0
SCALE	X.XX±.006(0.15)	.XX'±1'	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		
SIZE	X.XXX±.004(0.10)	.XXX'±0.5'	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
5:1	A4		CHERRY	28/JUN/13			